

**ABSTRACT OF THE DISCLOSURE**

It is intended to reliably form high-quality via-hole conductor with less variation, and to realize a circuit forming board having excellent connection reliability. It provides a conductive paste comprising primary particles and  
5 agglomerate of primary particles, conductive particles of 0.5 to 20  $\mu\text{m}$  in average particle diameter and 0.07 to 1.7  $\text{m}^2/\text{g}$  in specific surface area, and a binder based on thermosetting resin, and also provides an inexpensive circuit forming board with high connection reliability by using the paste.